Product Change Notification / ASER-10MDZB313

Date:

12-Jul-2023

Product Category:

Crypto Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5370 Final Notice: Qualification of S703LS as an additional die attach material for selected AT88S and AT88A device families available in SCC (12.6x11.4x0.58mm) package.

Affected CPNs:

ASER-10MDZB313_Affected_CPN_07122023.pdf
ASER-10MDZB313_Affected_CPN_07122023.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of S703LS as an additional die attach material for selected AT88S and AT88A device families available in SCC (12.6x11.4x0.58mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	AIC Semiconductor	AIC Semiconductor	AIC Semiconductor

	Sdn Bhd (AIC)	Sdn Bhd (AIC)	Sdn Bhd (AIC)
Wire Material	Au	Au	Au
Die Attach Material	2035SC	2035SC	S703LS
Molding Compound Material	1650	1650	1650
Lead-Frame Material	Epoxy Glass Film base with Copper	Epoxy Glass Film base with Copper	Epoxy Glass Film base with Copper

Impacts to Data Sheet: None

Change Impact None

Reason for Change: To improve on time delivery performance by qualifying S703LS as an additional die attach material.

Change Implementation Status: In Progress

Estimated First Ship Date: August 30, 2023 (date code: 2335)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	December 2022					**>**	**July 2023**					**August 2023**				
Workweek	49	50	51	52	53		26	27	28	29	30	31	32	33	34	35
Initial PCN Issue Date			X													
Qual Report Availability									X							
Final PCN Issue Date									X							
Estimated Implementation Date																X

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: December 09, 2022: Issued initial notification.

March 16, 2023: Re-issued initial notification to update the Die attach material from S703LT to S703LS. Update the timetable summary to reflect new qualification date from December 2022 to April 2023.

July 13, 2023: Issued final notification. Attached Qual Report. Added the estimated qualification report on August 30, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN ASER-10MDZB313 Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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